Contribution ID: 37 Type: Poster

Diffusion bonding of Al 6061and Cu by hot isostatic pressing

Wednesday, 6 December 2017 18:00 (2 hours)

In this work, diffusion bonding between Aluminum and Copper were successfully performed by hot isostatic pressing (HIP). In order to improve the strength of diffusion bonding joint, different thickness of pure Nickel foils was used as an intermediate layer. The microstructure of the interface between Aluminum and Copper was investigated using X-ray diffraction (XRD) technique, secondary electron microscopy (SEM), and the mechanical property evacuated through nanoindentation test.

Please choose topic

HIP Process

Primary author: Mr TENG, qing (Huazhong University of Science and Technology)

Co-authors: Mr CAI, Chao (Huazhong University of Science and Technology); Mr XUE, pengju (Huazhong University of Science and Technology); Mr WEI, qingsong (Huazhong University of Science and Technology); Mr SHI, yusheng (Huazhong University of Science and Technology)

Presenter: Mr TENG, qing (Huazhong University of Science and Technology)

Session Classification: Poster Session

Track Classification: HIP Process